

CLAIMS:

1. An electronic device having
 - a body having a cavity with an inner side and an aperture
 - a semiconductor element provided with contacts, which semiconductor element is present in the cavity and at least part of its contacts are situated at the aperture of the cavity;

5 characterized in that the contacts are in electric contact, via conductive connecting pieces, with contact surfaces, which contact surfaces are anchored in electrically insulating material.
- 10 2. An electronic device as claimed in claim 1, wherein the body comprises an electrically insulating material which encapsulates the semiconductor element with the exclusion of the aperture.
- 15 3. An electronic device as claimed in claim 1, wherein the electrically insulating material forms an envelope, which also fills the cavity.
4. An electronic device as claimed in claim 3, further comprising a thermally conductive layer which is in thermal communication with the semiconductor element and is at least partly situated on the inner side of the cavity.
- 20 5. An electronic device as claimed in claim 4, characterized in that the body is a multilayer substrate of insulating material with conductive intermediate layers, the thermally conductive layer being part of an intermediate layer of the multilayer substrate.
- 25 6. An electronic device as claimed in claim 1, characterized in that further components are present, which are connected, as desired with the contacts of the semiconductor element by electroconductive interconnects.

7. A method of manufacturing an electronic device comprising a body having a cavity with an inner side and an aperture, and a semiconductor element provided with contacts, which semiconductor element is present in the cavity and at least part of its contacts are situated at the aperture of the cavity;

5 which method comprises the steps of:

- providing the body with the semiconductor element and a cover, which cover comprises a patterned layer of electroconductive material and a sacrificial layer,

- assembling the body and the cover in such a manner that the contacts of the semiconductor element are connected to the patterned layer of the cover

10 - providing an envelope between the cover and the body, the patterned layer being mechanically anchored in the envelope, and

- removing the sacrificial layer from the cover.

8. A method as claimed in claim 7, wherein the body with the semiconductor element is provided by:

15 - providing the semiconductor element on a temporary carrier, the contacts being at the side of the temporary carrier;

- molding the semiconductor element, therewith forming the body of electrically insulating material; and

20 - removal of the temporary carrier, therewith providing the aperture.

9. A method as claimed in claim 7, wherein the body is provided with a thermally conductive layer at the inner side of the cavity, which is in thermal communication with the semiconductor element, and wherein the body with the semiconductor element is provided by placing the semiconductor element on the thermally conductive layer of the body.

10. A method of manufacturing an electronic device comprising a body having a cavity with an inner side and an aperture, and a semiconductor element provided with contacts, which semiconductor element is present in the cavity and at least part of its contacts are situated at the aperture of the cavity; which method comprises the steps of:

30 - providing the body and a cover, at least a part of the inner side of the cavity being provided with a thermally conductive layer, and said cover comprises a patterned layer of electroconductive material and a sacrificial layer,

- placing the semiconductor element on the patterned layer of the cover;
- assembling the body and the cover in such a manner that the semiconductor element is in thermal communication with the thermally conductive layer, and that contacts of the semiconductor elements are connected to the patterned layer of the cover;
- 5 - providing an envelope between the cover and the body, the patterned layer being mechanically anchored in the envelope, and
- removing the sacrificial layer from the cover.

11. A method as claimed in claim 8, 9 or 10, characterized in that a patterned sub-
10 layer is present in the cover, between the patterned layer and the sacrificial layer, which patterned layer and which sub-layer comprise a first and a second pattern, which patterns are mutually separated by a recess having a larger diameter in the plane of the sub-layer than in the plane of the patterned layer.

15 12. A method as claimed in claim 8 or 10, characterized in that the body comprises a plurality of cavities and is assembled with a suitable cover after placement of semiconductor elements and that after removal of the sacrificial layer, the assembly of body and cover is separated into individual electronic devices.

20 13. A method as claimed in claim 9 or 10, characterized in that the body comprises glass, and the cavity is formed by means of a blasting technique, after which a thermally conductive layer is applied on the inner side of the cavity, which layer extends to beyond the cavity.

25 14. A method as claimed in claim 9 or 10, characterized in that the body is provided by deforming a foil of a thermally conductive layer and a sacrificial layer so as to form the cavity, the sacrificial layer being removed after the envelope has been provided between the body and the cover.